

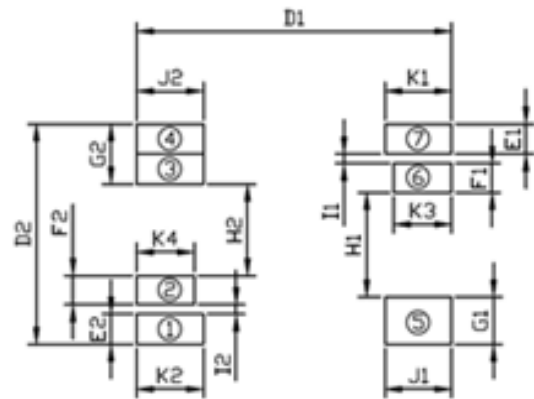
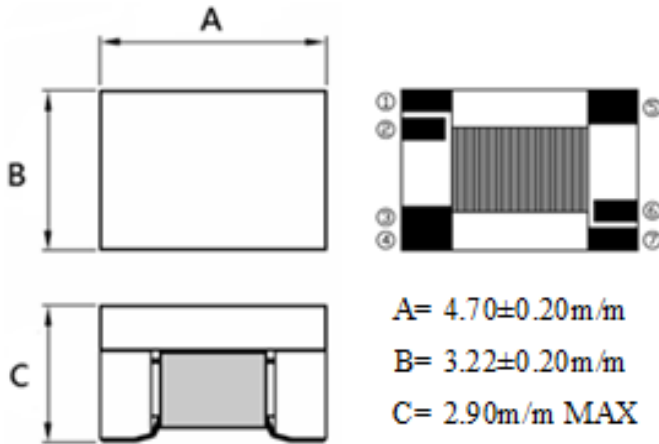
FXF4532-381-7P TYPE

●FEATURE

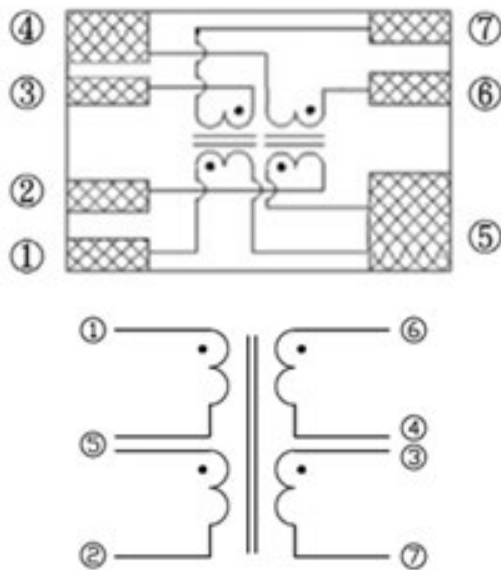
1. IEEE 802.3 Ethernet compatible
2. Pair with common mode choke F4P2012-801 for EMI reduction

●Shape and Dimension(unit:mm)

●Schematics and Land Patterns(mm)



SCHEMATIC:



D1=	5.00m/m	I1=	0.45m/m
D2=	3.23m/m	I2=	0.37m/m
E1=	0.33m/m	J1=	0.95m/m
E2=	0.27m/m	J2=	0.90m/m
F1=	0.34m/m	K1=	0.97m/m
F2=	0.28m/m	K2=	0.97m/m
G1=	0.77m/m	K3=	0.85m/m
G2=	0.77m/m	K4=	0.85m/m
H1=	1.61m/m		
H2=	1.54m/m		

● Specification

ITEM	Chip LAN transformers, 1812, 380uH
FENG JUI P/N.	FXF4532-381-7P
ELECTRICAL REQUIREMENTS	<p>INDUCTANCE(P1-2, or P6-7(P3-4short)): 380uH min@100KHz</p> <p>Capacitance(pF): 35pF typ.(Pin 5-3 short 3-4)</p> <p>Turn Ratio: 1:1(±3%)(P1-2,3-4 short 6-7)</p> <p>Hi pot (P1-6, short 3-4): 1500Vac, 60 sec</p> <p>Insertion loss: -1.5dB MAX (1~100MHz)</p>

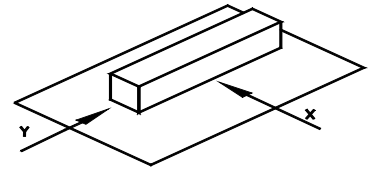
TEST METHOD:

TEST EQUIPMENT	HP4294A/E5071C
TEST FREQUENCY	SEE ELECTRICAL DETAILS

GENERAL CHARACTERISTICS

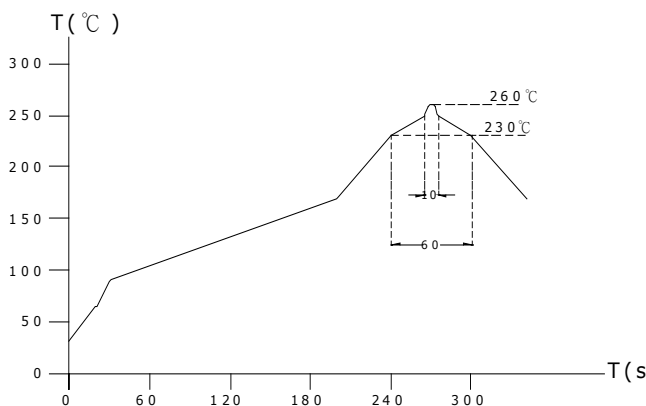
1. Operating temperature range: -40 TO + 85°C (Includes temperature when the coil is heated)
2. External appearance: On visual inspection, the coil has no external defects.
3. Terminal strength: After soldering. Between copper plate and terminals of coil. Push in two directions of X.Y withstanding at below conditions.

Terminal should not peel off. (refer to figure at right) 5N. 0N 60 sec.



4. Temperature characteristics: Inductance coefficient $(0\sim 2,000)\times 10^{-6}/^{\circ}\text{C}$ (-25~+80°C degree Celsius), inductance deviation within $\pm 5.0\%$, after 96 hours.
5. Humidity characteristics (Moisture Resistance): Inductance deviation within $\pm 5\%$, after 96 hours in 90~95% relative humidity at $40 \pm 2^{\circ}\text{C}$ and 1 hour drying under normal condition.
6. Vibration resistance: Inductance deviation within $\pm 5\%$, after vibration for 1 hour. In each of three orientations at sweep vibration (10~55~10 Hz) with 1.5mm P-P amplitudes.
7. Shock resistance: Inductance deviation within $\pm 5\%$, after being dropped once with 981m/s^2 (100G) shock attitude upon a rubber block method shock testing machine, in three different orientations.
8. Resistance to Soldering Heat: 260°C , 10 seconds (See attached recommend reflow)
9. Storage condition: Temperature Range: $0^{\circ}\text{C} \sim 35^{\circ}\text{C}$; $-40^{\circ}\text{C} \sim 85^{\circ}\text{C}$ (after PCB), Humidity Range: 50% ~ 70% RH
10. Use components within 12 months. If 12 months or more have elapsed, check solderability before use.
11. Reflow profile recommend:

Lead-free heat endurance test



Lead-free the recommended reflow condition

